

List of designations

- 10 semiconductor substrate or semiconductor wafer or semiconductor chip
- 11 carrier layer or barrier layer, for example comprising titanium
- 12 conductive layer, in particular interconnect level
- 13 solder layer, in particular interconnect
- 14 height of solder structure or vertical extent of solder on an interconnect portion of the interconnect level
- 15 width of solder structure or horizontal extent of solder on an interconnect portion of the interconnect level
- 16 side wall of the interconnect level
- 17 interconnect portion of the interconnect level
- 18 terminal or connecting device of the interconnect level

- 24 height of solder structure or vertical extent of solder on a terminal or connecting device of the interconnect level
- 25 width of solder structure or horizontal extent of solder on a terminal or connecting device of the interconnect level

- 30 solder balls (solder bumps)
- 31 mechanical chip connection
- 32 interposer substrate
- 33 chip cladding
- 34 printed circuit board
- 35 interconnect on interposer substrate with via hole

- 40 carrier layer, preferably with Ni
- 41 protective layer, for example of Au